

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (<=)	Hole Tolerance (>=)
□	1	33.75mil (1.010mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r430_170x101_356x88			
□	2	27.56mil (0.700mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)			
○	2	28.92mil (0.760mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r380_150x76_305x75			
○	2	50.00mil (1.270mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c127x127			
×	2	84.00mil (2.134mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c40x213x50			
○	2	105.91mil (2.690mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0m269m10			
○	2	125.59mil (3.200mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c320x320x320p0			
○	5	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c221x60			
⊘	8	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
⊘	10	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
⊘	18	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c104x71			
⊘	20	66.53mil (1.700mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c260x170x260p0			
⊘	30	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c64x38x64			
⊘	71	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)			
▽	1079	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)	Rounded	(Mixed)			
1284 Total											

Slot definitions : Rounded Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Rounded Path Length + Tool Size + Slot length as defined in the PCB Layout



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DC276	REV: C	SUN REV: 1a5319a59745b3b6442724175f06a0812f21cc0f
LAYER NAME = Fabrication Drawings			
PLOT NAME = Fabrication Drawing	GENERATED : 10/8/2024 1:01:54 PM	TEXAS INSTRUMENTS	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric 1	FR4-370HR	5.00mil	3.96	
2	L2 GND	CF-004	1.40mil		
	Dielectric 3	FR4-370HR	3.00mil	3.72	
3	L3 Signal	CF-004	1.40mil		
	Dielectric 9	PP-006	2.80mil	4.1	
4	L4 GND	CF-004	1.38mil		
	Dielectric 7	PP-006	2.80mil	4.1	
5	L5 PWR	CF-004	1.38mil		
	Dielectric 5	FR4-370HR	3.00mil	3.86	
6	L6 GND	CF-004	1.40mil		
	Dielectric 1	FR4-370HR	12.00mil	4.14	
7	L7 GND	CF-004	1.40mil		
	Dielectric 6	FR4-370HR	3.00mil	3.86	
8	L8 PWR	CF-004	1.38mil		
	Dielectric 8	PP-006	2.80mil	4.1	
9	L9 GND	CF-004	1.38mil		
	Dielectric 10	PP-006	2.80mil	4.1	
10	L10 PWR	CF-004	1.40mil		
	Dielectric 4	FR4-370HR	3.00mil	3.72	
11	L11 GND	CF-004	1.40mil		
	Dielectric 2	FR4-370HR	5.00mil	3.96	
12	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

Total board thickness: 62.71mil

M10 Fab Notes

DESIGN INFORMATION

MIN. TRACK WIDTH: 4 MIL
MIN. CLEARANCE: 5 MIL
MIN. VIA PAD SIZE: 18 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
☐ HYBRID STACKUP ☒ UNIFORM STACKUP
☒ ISOLA FR4-370HR OR FR4-408
☐ Megtron 4 OR Isola I-Speed
☐ Megtron6 OR Isola MT-40 OR Nelco MW-1000
☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER 92 MIL +/-10%
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER
SOLDER RESIST COLOR: ☐ GREEN ☒ OTHER RED
☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ MM. TIN/SILVER OR EQUIV ☐ HARD GOLD (30u)
☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
☒ 16 MIL & SMALLER VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
☒ OUTER LAYER TRACKS 9 MIL WIDE REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
☒ OUTER LAYER TRACKS 6 MIL WIDE WITH 4 MIL AIR GAP REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE
☐ INNER LAYER XX & XX TRACKS XX MIL WIDE REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
☐ INNER LAYER TRACKS XX MIL WIDE WITH XX MIL SPACE REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE:
ADC3669EUM

DESIGNED FOR:
Public Release

FILE NAME:
ADC3669EUM_PcbDoc

ENGINEER:
GBR

LAYOUT BY:
GBR

SCALE: 1.00

ALTIM DESIGNER VERSION:
24.4.1.13

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